

HIGH HEAT FORMULATIONS

Resins and additives for waterborne and solventborne systems

APPLICATION/ BINDER TYPE	DRYING/ CURING CONDITION	SYSTEM	SPECIALTY BINDERS	HARDENER	THERMAL INSULATION	DEAERATION/ DEFOAMING	SUBSTRATE WETTING	PIGMENT WETTING	RHEOLOGY	MATTING
Thermal insulation coating *up to ~250 °C	Ambient drying and/or stoving	Water-borne	TEGO® Therm L 300 ●		TEGO® Therm HPG 4000 ● TEGO® Therm HPG 6806 ●					
Decorative coatings Silicone-Polyester *up to ~250 °C	Stoving	High Solid Solvent-borne	SILIKOFTAL® HTT							
		Solvent-borne	SILIKOFTAL® HTL 3/MPA SILIKOFTAL® HTF MPA/MBA							
		Water-borne	SILIKOFTAL® HTW 3				SURFYNOL® 440			
Heat & chemical resistant coatings Silicone-Epoxy *up to ~350 °C	Ambient drying and/or stoving	Solvent-borne	SILIKOPON® EC			TEGO® Airex 900			AEROSIL® R 972 AEROSIL® R 974	ACEMATT® OK 412 ACEMATT® OK 500
High-Heat coatings Silicone *up to ~650 °C	Ambient curing	High Solid Solvent-borne	SILIKOPHEN® AC 900 SILIKOPHEN® AC 1000	TEGO® Cure 100 ●		TEGO® Airex 900	TEGO® Wet 270	TEGO® Dispers 628		
	Ambient drying and/or stoving	Solvent-borne	SILIKOPHEN® P 50/X	TEGO® Cure 100 ●		TEGO® Airex 900	TEGO® Wet 270	TEGO® Dispers 670		
		High Solid Solvent-borne	SILIKOPHEN® P 80/X SILIKOPHEN® P 80/MPA	TEGO® Cure 100 ● TEGO® Cure 100 ●						
		Water-borne	SILIKOPHEN® P 40/W				TEGO® Wet 270	TEGO® Dispers 740 W TEGO® Dispers 750 W		

● new product

*temperature resistance depends on total coating formulation

For food contact application – please click [here](#) to visit our Regulatory Guidance webpage

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